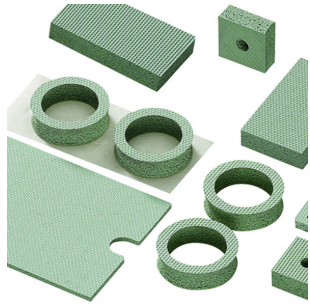


# Data sheet Product WSF 16



Accessories for electronic components>Thermal interface material>Heat conductive foam and gel foils

- elastomer foam with closed cell structure
- good heat conductor e.g. between components, heatsinks and casing parts
- electrical insulating
- can be compressed even with a low contact pressure
- absorbs shocks and vibrations

### Thermal resistance at 3.2 mm material thickness:

|   |         |     |      |      |
|---|---------|-----|------|------|
| compression [%]                             | contact | 10  | 25   | 50   |
| contact pressure [psi]                      | >1      | 5   | 12   | 34   |
| $R_{th}$ [K/W] (1 in <sup>2</sup> x 3.2 mm) | 6       | 4.5 | 2.5  | 1    |
| heat conductivity [W/mK]                    | 0.3     | 0.4 | 0.45 | 0.65 |

- **WSFS 635** double sided adhesive and **WSF** self-adhesive upon request
- according to NASA gas emission requirements

## Features

material:

foam film

Material:

100mm 100mm

material thickness:

**1.6<sup>±0,400</sup> mm**

version:

**non adhesive**

colour:

**green**

density:

**1.105 g/cm<sup>3</sup>**

hardness:

**13 Shore A**

temperature range:

**-62°C ... +205°C**

thermal conductivity:

**0.108 W/m·K (substrate)**

compression, 25%:

**18 psi**

elongation:

**150 %**

tear strength:

**120 psi**

dielectric strength:

**4 kV/mm**

class of inflammability:

**UL 94 V-1 (at thickness ≥3.2mm)**

type of delivery:

- **plates, usable area 914x914mm**
- **other dimensions upon request**